

Amendments to the Specification

Please **replace** the following paragraph beginning at page 1, line 5, with the following **rewritten** paragraph:

-- This application claims the benefit, under 35 U.S.C. § 365 of International Application PCT/US03/02930, filed January 31, 2003, which was published in accordance with PCT Article 21(2) on August 7, 2003 in English and which claims the benefit of ~~This U.S. non-provisional patent application claims the benefit of and/or priority to U.S. United States~~ Provisional patent application serial No. 60/354,070, filed January 31, 2002 entitled "~~Circular Die Bond Pads For Routing Optimization on a Mating Printed Circuit Board~~"; U.S. ~~United States~~ Provisional patent application serial No. 60/354,069, filed January 31, 2002 entitled "~~Die Bond Pad Placement Optimization For Minimal BGA PCB Layers~~"; and U.S. United States Provisional application serial No. 60/353,804, filed January 31, 2002 entitled "~~Die Size Minimization by Using Flip Chip Bond Pad Placement and PCB Routing For Power and Ground~~". --